



Advances in MEMS Sensors

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Message from the Guest Editors

Recent advances in MEMS (microelectromechanical systems) sensor technologies have played important roles in many fields. Individual or integrated sensors and their networks have enabled the efficient use of information and resources while facilitating the realization of harsh and dangerous tasks in different fields. Methods and protocols designed for operable and profitable devices have also driven the processing of relevant information-oriented sensor technologies (chemical and physical sensors) towards greater efficiency. The MEMS research community has devoted great efforts to advancing the state-of-the-art sensor technologies by improving microfabrication processes and microsystem designs. In this Special Issue, research considering recent advances in MEMS sensors will be highlighted.





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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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